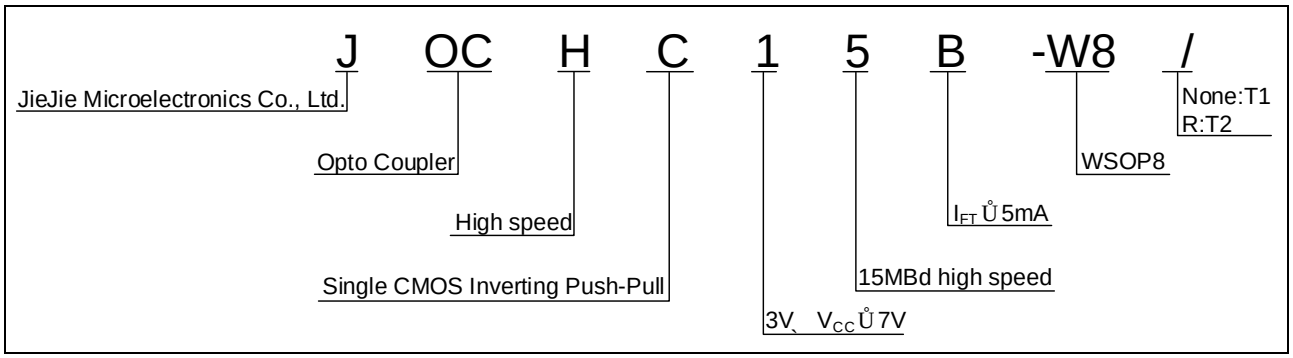
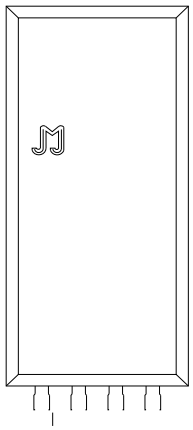
	Time to Logic Low						
	Propagation Delay Time to Logic High	TPLH	I_F=7mA,C_L=15pF	-	55	100	ns
	Common Mode Transient Immunity at Logic High	CM_H	I_F=0mA, V_{CM}=1000Vpp, C_L=15pF, V_{CC}=5V	20	-	-	kV/μs
	Common Mode Transient Immunity at Logic Low	CM_L	I_F=7mA, V_{CM}=1000Vpp, C_L=15pF, V_{DD} '	à CM			

ORDERING INFORMATION



Packing Quantity	
Option	**Quantity**

MARKING



Characteristics Curves

FIG.1: Forward Current vs. Forward Voltage

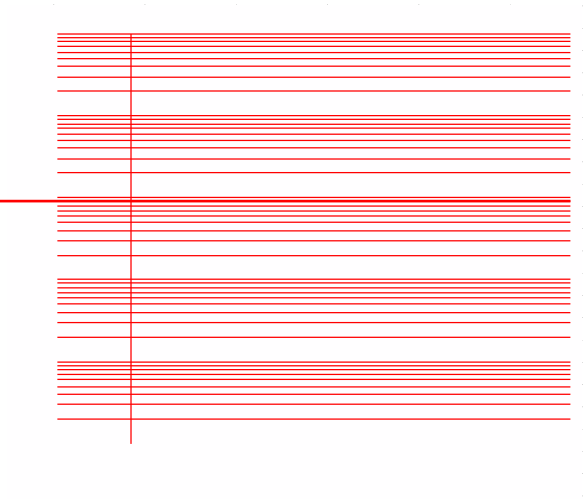


FIG.2: Max. Allowable LED Forward Current vs. Ambient Temperature

FIG.7: Propagation Delay vs. Ambient Temperature

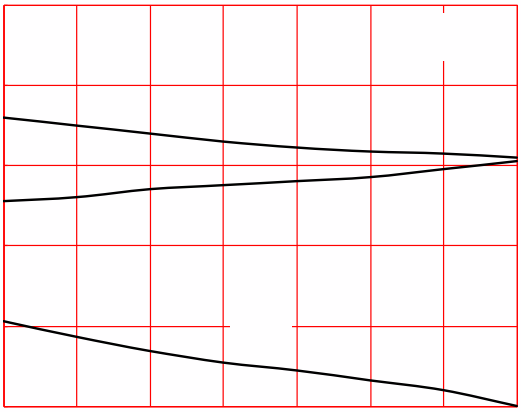
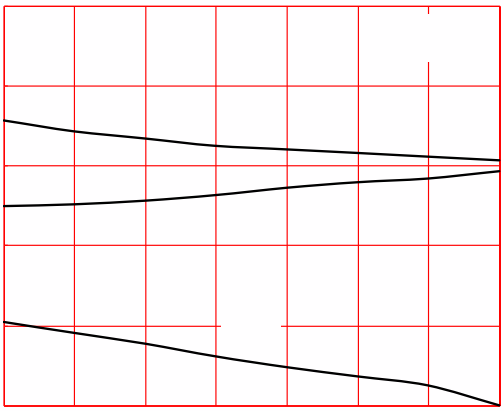
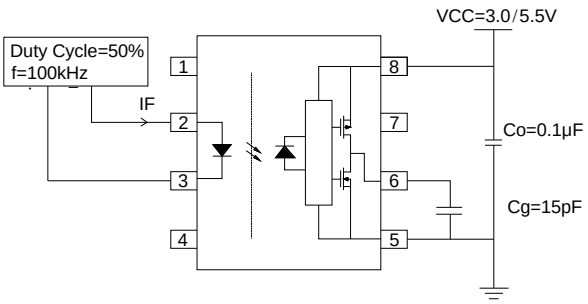


FIG.8: Propagation Delay vs. Ambient Temperature



TEST CIRCUITS

Fig.9: Test Circuits for TPHL, TPLH, tr, tf



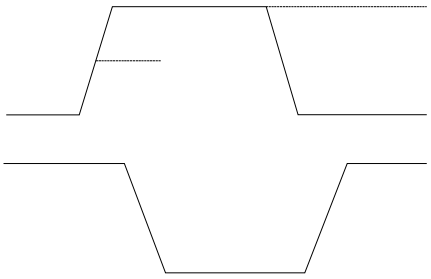
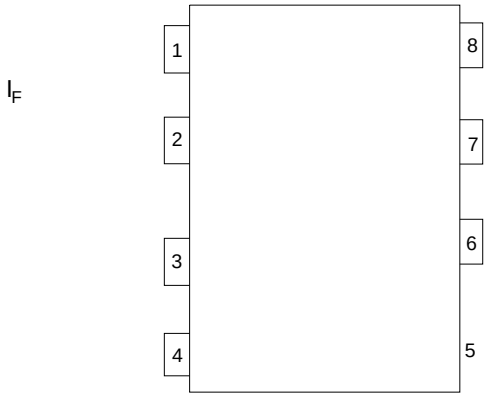
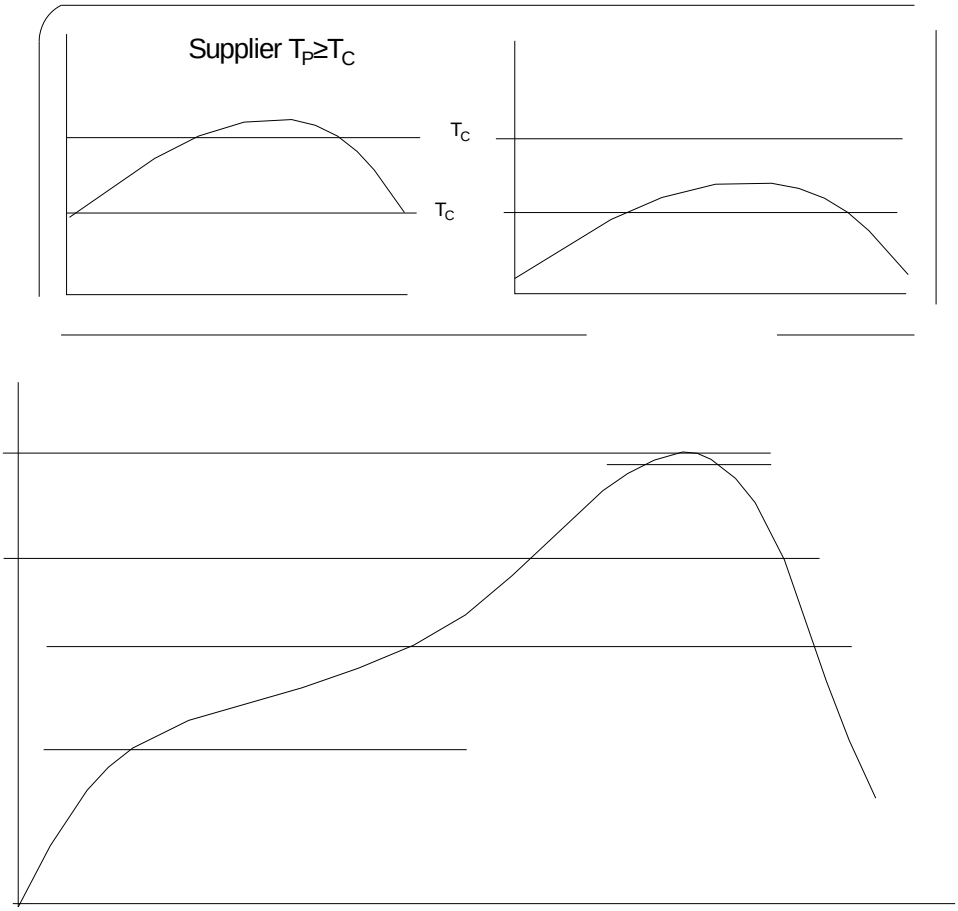


Fig.10: CMTI Test Circuit Recommendations



RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)

REFLOW INFORMATION



Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.

2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.

3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.

4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.

5. The component has a shelf life of one year when stored under standard conditions.

6. Recommend storage Temp.: 0~40°C;

Recommend storage humidity: <60%;

MSL level: MSL 1